AGENDA

Event: **Semiconductor Packaging Technology Symposium**
Date: **Thursday, October 23, 2014**
Location: **Biltmore Hotel, Santa Clara, CA**

7:00 am **Registration opens**

7:50 am – 8:00 am **Welcome and Introduction**

Session 1: Wafer Fab, Packaging, and Test – Supply Chain Coordination as a Critical Capability
Session Leader: Phil Marcoux, Fab Owners Association

8:00 am – 8:30 am **Morphing the Semiconductor Outsourcing's Business Model: Wafer Level Packaging**
Jim Walker, Research Vice President of the Semiconductor Manufacturing and Emerging Technologies Group, Gartner
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8:30 am – 9:00 am **Supply Chain Benchmarking Now Focused on Packaging**
Ariel Meyuhas, COO, The MAX Group

9:00 am – 9:30 1m **An IDM's Integration and Partnership with the OSAT Supply Chain**
James G. Gandenberger, Vice President of Worldwide Operations & Foundry Business Unit, Micrel, Inc.

9:30 am – 10:00 am **Break and Exhibits**

Session 2: Design Considerations for Advanced Package Development
Session Leader: John Xie, Altera

10:00 am – 10:30 am **Optimize Product Cost and Performance with System-level 3D Chip, Package, Board Co-design**
James Church, Solutions Architect, R&D Center, Zuken

10:30 am – 11:00 am **Considerations in High-Speed High Performance Die-Package-Board Co-Design**
Jenny Jiang, Principal Engineer of SIPI, Altera Corporation

11:00 am - 11:30 am **Will IoT (Internet of Things) Drive 2.5/3D IC Revenue Growth and Change our Lives?**
Herb Reiter, Founder, eda2asic Consulting, Inc.

11:30 pm – 12:30 pm **Lunch and Exhibits**

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12:30 pm – 1:00 pm	**Keynote: Transforming Electronic Interconnect** Tim Olson, Founder & CTO, Deca Technologies

Session 3: Pushing the Envelope on IC Package Manufacturing
Session Leader: Joel Camarda, SemiOps

1:00 pm – 1:30 pm	**Silver Sintering for Power Electronics** Jenny (Jiong) England, Principal Technical Service Engineer Henkel Electronics Materials
1:30 pm – 2:00 pm	**The Future of Packaging - The Relevance of Wire Bonding** Ivy Qin, Process Director, Kulicke & Soffa Industries, Inc.
2:00 pm – 2:30 pm	**Advances in Medical Device Package Manufacturing** Ed Binkley, CTO, Promex Industries
2:30 pm – 3:00 pm	**Advanced Packaging's Interconnect Technology Process Shift and Direction** Jay Hayes, Director of Business Development – Bumping & Flip Chip Unisem

3:00 pm – 3:30 pm	**Break and Exhibits**

Session 4: Enabling Multi-Die Packaging as a Mainstream Solution
Session Co-Leaders: Jeff Demmin, STATSChipPAC and Ivor Barber, Xilinx

3:30 pm – 4:00 pm	**Challenges of Building RF Multi-chip Modules** Frank Juskey, Senior Member of the Technical Staff, Advanced Technology Development Group, TriQuint Semiconductor
4:00 pm – 4:30 pm	**MCM Package Development for In-Vehicle Infotainment System** Terry Kang, Sr. Packaging Development Manager, NVIDIA
4:30 pm – 5:00 pm	**Thermal Management in High-Performance Integrated 3D TSV Logic/Memory Systems** Tom Gregorich, Vice President of Package Technology, Micron

5:00 pm – 6:30 pm	**Reception**